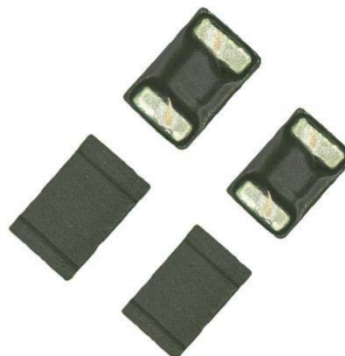


Wire Wound Chip Inductor



◆ Features

- 1、Small chip suitable for surface mounting;
- 2、High Q value and high self-resonant frequency with ceramic material;
- 3、Tight inductance tolerance and stable inductance; at high frequency;
- 4、RoHS Compliant.



◆ Application

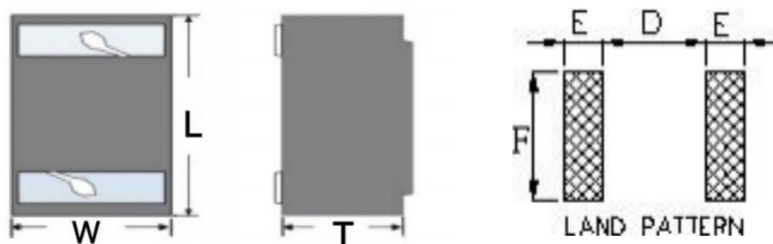
- 1、High frequency circuit in telecommunication and other equipments;
- 2、Mobile phones such as GSM, CDMA, PDC, etc;
- 3、Bluetooth, W-LAN, Broadband network.

◆ PRODUCT IDENTIFICATION

SCW 1608 Q 1R0 M S T
(1) (2) (3) (4) (5) (6) (7)

- (1) Series Type
- (2) Chip Size (mm) :Length X Width
- (3) Material Code
- (4) Inductance: 1R0=1.0uH 100=10uH
Inductance Tolerance: J=±5%; K=±10%; M±20%;
- (5) Company Code
- (6) Packaging: Tape Carrier Package

◆ SHAPE AND DIMENSIONS (unit : mm)



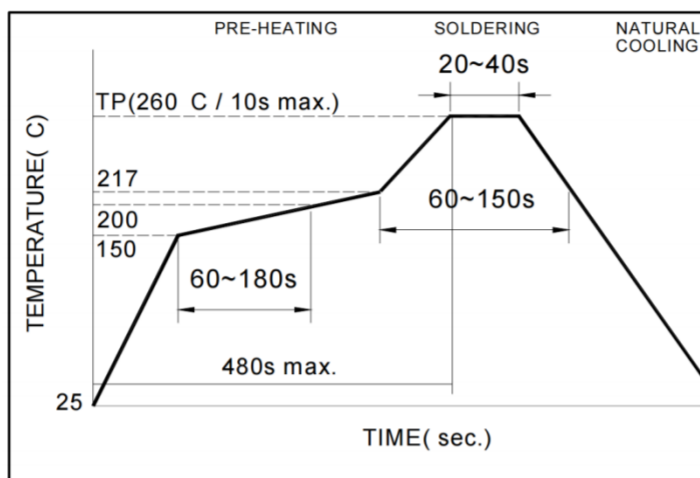
Series	L	W	T	E	F	D
SCW1608Q	1.60±0.15	1.1±0.15	1.0±0.15	0.64Typ	1.02Typ.	0.64Typ.

◆ Specification

Part Number	Inductance	Test Condition	Q	SRF (Min.)	DCR $\pm 30\%$	Isat (Typ)	Irms (Typ)
	μH	MHz	(Typ)	MHz	$\Omega(\text{Max})$	mA	mA
SCW1608Q1R0MST	1.0 $\pm 20\%$	1.0	9	350	0.21	1100	720
SCW1608Q1R5MST	1.5 $\pm 20\%$	1.0	9	300	0.39	650	520
SCW1608Q2R2MST	2.2 $\pm 20\%$	1.0	9	250	0.46	680	480
SCW1608Q4R7MST	4.7 $\pm 20\%$	1.0	9	100	0.7	450	400
SCW1608Q6R8MST	6.8 $\pm 20\%$	1.0	9	50	1.25	360	300
SCW1608Q100MST	10 $\pm 20\%$	1.0	9	25	1.3	270	380
SCW1608Q150MST	15 $\pm 20\%$	1.0	9	25	2.0	270	230
SCW1608Q220MST	22 $\pm 20\%$	1.0	9	10	3.9	220	160

◆ SOLDERING CONDITIONS

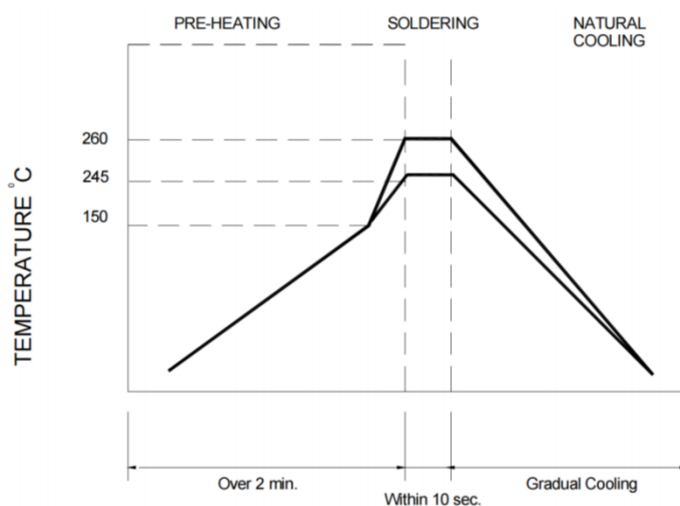
**Figure 1.
Re-flow
Soldering
(Lead
Free)**



Note:

- Preheat circuit and products to 150°C
- 260°C tip temperature (max)

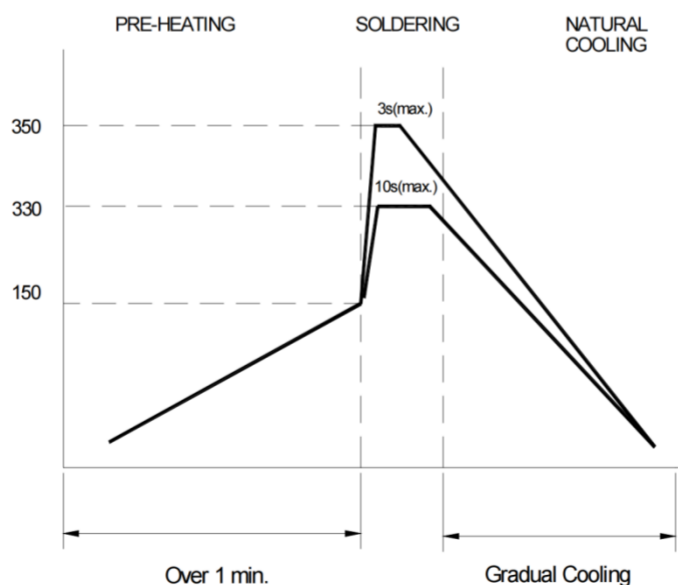
**Figure 2.
Wave
Soldering**



Note:

- Never contact the ceramic with the iron tip
- 1.0mm tip diameter (max)

**Figure 3.
Hand
Soldering**

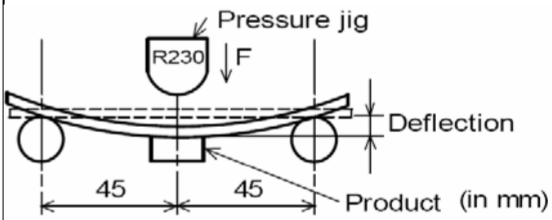


Note:

- Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 3 sec.

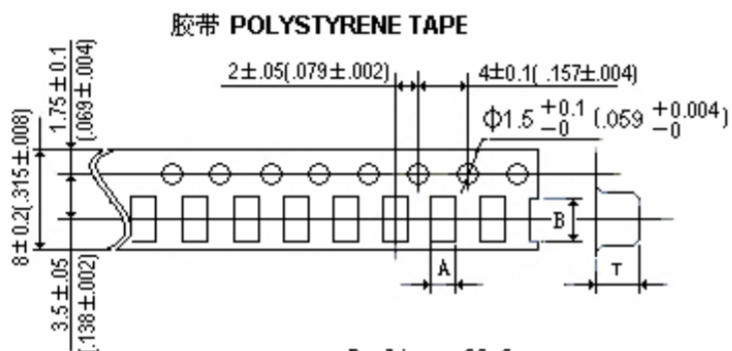
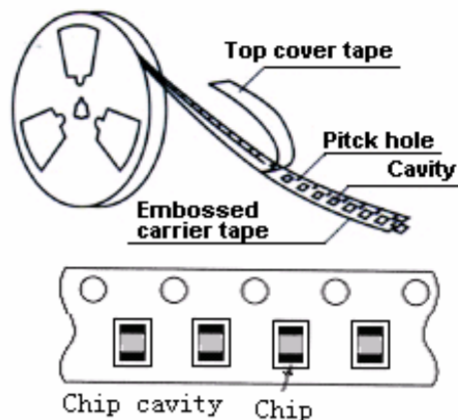
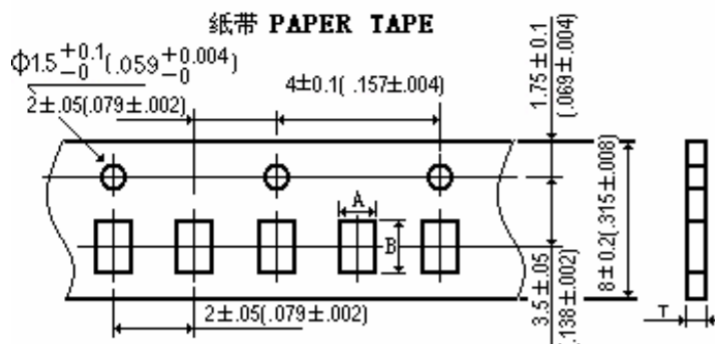
◆ RELIABILITY TEST

TEST ITEM	SPECIFICATION	TEST CONDITION
Rating current	According to product specifications	Current sources:33010D
Inductance	According to product specifications	Test Frequency:0.252~250MHz Test Equipment:HP4291A 、 HP4286A 、 HP4287A 、 HP4284A Test Fixture:16193Aor16334A
Q	According to product specifications	Test Frequency:0.252~1500MHz Test Equipment:HP4291A、 HP4286A、 HP4287A Test Fixture:16193Aor16334A
RDC	According to product specifications	Test Equipment:HP4263B
SRF	According to product specifications	Test Equipment:HP4291A Test Fixture:16193A
Solderability	The metalized area must have more then 90% of solder coverage	Soldering Temp:230±5℃ Dipping time:5±1S
Resistance to soldering heat	No evidence of mechanical damage The mealized arer must have more then 75%of solder coverage Inductance change,less than±5% Q change less than±10%	Soldering Temp:260±5℃ Dipping time:10±1S
Thermal Shock	No evidence of mechanical damage, Inductance change less than±5%, Q change less than±10%	A cycle contain:Step1:-40℃ , 30Min Step 2:85℃ , 30Min Cycle Times:10

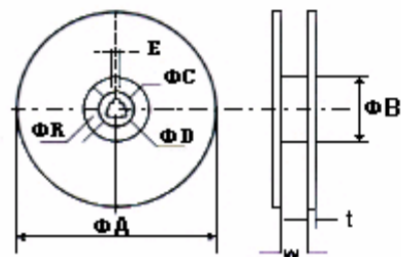
TEST ITEM	SPECIFICATION	TEST CONDITION
High Temperature Storage	No evidence of mechanical damage, Inductance change less than $\pm 5\%$, Q change less than $\pm 10\%$	Test Temperature: $125 \pm 2^\circ\text{C}$ (Ceramic core) $85 \pm 2^\circ\text{C}$ (Ferrite core) Test Time: 96 ± 2 Hours
Low Temperature Storage	No evidence of mechanical damage, Inductance change less than $\pm 5\%$, Q change less than $\pm 10\%$	Test Temperature: $-40 \pm 2^\circ\text{C}$ Test Time: 96 ± 2 Hours
Moisture Resistance	No evidence of mechanical damage, Inductance change less than $\pm 5\%$, Q change less than $\pm 10\%$	Test Temperature: $50 \pm 2^\circ\text{C}$ Test Time: 100 Hours relative humidity: 90~95%
Vibration	No evidence of mechanical damage, Inductance change less than $\pm 5\%$, Q change less than $\pm 10\%$	Amplitude: 1.5mm X、Y、Z each direction for 1 Hour and 45min Frequency range: 10~55~10Hz(min)
Component Adhesion	No evidence of mechanical damage No evidence of peel off or broken Keep continuity of Winding	Force: 2Kg Test Time: 5 ± 1 sec
Resistance to bend	No evidence of mechanical damage	Camber: 20mm Test Board: Glass-Epoxy board Thickness: 8mm 
Life	No evidence of mechanical damage, Inductance change less than $\pm 5\%$, Q change less than $\pm 10\%$	Test Temperature: $85 \pm 2^\circ\text{C}$ Test Time: 1000 Hours with rating current

◆ PACKAGING(unit: mm)

Tape



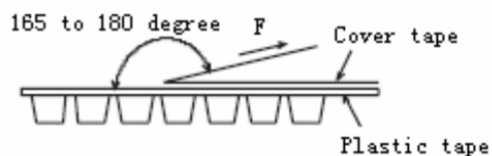
Reel Dimensions



Peeling off force

Full strength
0402~1210:20g~80g

Speed of peeling off:
300mm/min±10%



膠帶	A	B	T
0603	1.15	1.83	0.95

Type	ΦA	ΦB	ΦC	ΦD	E	W	t	R
0603	178	60	13	21	2	8.4	2	1

PACKAGING QUANTITY

Size	SCW1608Q Series
Quantity(pcs)	4,000